



Type Document	Product Specification	Revised /Edition	I
Date Issued	2010/03/31	Data Revised	2015/04/04
Subject : JS-ID0600-XX JS-ID0601H-XX JS-ID0601V-XX Pitch 0.6mm SMT Series Wire to Board Insulation Displacement Connector			Issued By: Engineering Dept.

*This specification is referred to 0.60mm SMT series
Wire to Board Insulation Displacement connector.*

本規格書內容係提供 0.60 mm SMT 系列產品相關參考，
其用途為電線端相接於電路板端之絕緣體刺破型連接器

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REV. (版次)	Revision Record (改版變更原因)	Date(日期)	EC No
B	增加漏電流小於0.5mA偵測值	2011/05/30	EC2011-05-090
C	修訂 插入力與拔出力規格值	2012/11/07	EC2012-11-007
D	1.增加鍍層以及無鹵素選項 2. 迴焊適用溫度250C +5/-0C ; 修改為260C Max. 10C	2012/11/14	EC2012-11-014
E	增列JS-ID0601V 樣品圖示	2013/01/24	EC2013-01-024
F	6.2 項增訂 Note : It is necessary to use the UV glue for the application of the wire retention force increasing 電線壓接之後為能夠使保持力提昇，可於必要時披覆 UV 膠	2013/07/10	EC2013-07-010
G	JS-ID0601H/V-XX(NM) ; JS-ID0601H/V-XX(G)原編碼修訂為 JS-ID0601H/V-XXM ; JS-ID0601H/V-XXG0	2013/08/07	EC2013-08-007
H	1.修訂 Solder Ability 附註 Tin Plated : 95% / Gold Plated : 75% 2.增訂(IPC/JEDEC J-STD-020D.1) 參考規範	2013/11/25	EC2013-11-025



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1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):

Product Name(產品名稱)		Part Number(零件型號)	Drawing Number(圖面型號)	
Housing		JS-ID0600-XX	JS-ID0600-XX	
Wafer	Straight	JS-ID0601V-XXXXXX	JS-ID0601V-XXXXXX	JS-ID0601V-XXXXNH
	Right Angle	JS-ID0601H-XXXXXX	JS-ID0601H-XXXXXX	JS-ID0601H-XXXXNH

Note: (xx) The number of the circuits. ; **XX** = Blank : Normal ; **NH**= Halogen Free

2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):

Part Name(零件名稱)		Material(材質)	Surface Finish(表面鍍層)
(IDC)Housing (電線端刺破型連接器)	Contacts (導體)	Copper Alloy	Tin-Plated
	Base (膠座)	LCP	UL 94V-0
Wafer (電路板端連接器)	Contacts (導體)	JS-ID0601H/V-XXXX	Tin Plated : Sn >100u" ; Ni >30u"
		JS-ID0601H/V-XXM	Mattn -Sn Plated : Sn >100u" ; Ni >30u"
		JS-ID0601H/V-XXG0	Gold Plated : Au >0.8u" ; Ni >30u"
	Solder Nail (固定片)	Brass	Tin Plated : Sn >100u" ; Ni >30u"
	Base (膠座)	LCP +40%Glass Fiber	UL 94V-0

3.0 Characteristic(產品特性):

Item(項目)	Standard(標準規範)
3.1 額定電流 Rated Current	0.2A AC/DC With AWG #36 is applied (相對適用於美國電線規格 UL1007 AWG #36)
3.2 額定電壓 Rated Voltage	30 V AC/DC
3.3 Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度範圍) Operating Temp.: -25°C~+85°C Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C以下溫昇) (置存於環境當中溫度範圍) Non – Operating Temp. : -25°C~+85°C
3.4 Applicable Wire 適用電線	3.4.1 (電線絕緣材質外徑)Insulation O.D. Ø0.29mm
	3.4.2 (金屬導體之型號) Conductor Construction Size: AWG #36
3.5 Applicable Printed Circuit Board Layout 適用電路板佈局設計	3.5.1 SMT Layout: 0.60 ± 0.05 mm per Pitch 表面黏著焊錫點間距
	3.5.2 SMT Layout: 0.40X0.60±0.05 mm for Pin Post 導體焊錫點面積
	3.5.3 SMT Layout: 0.70X1.05±0.05 mm for Solder Nail 固定片焊錫點面積



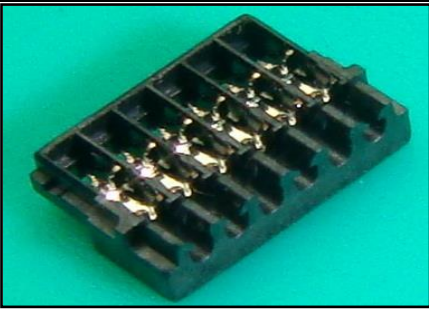
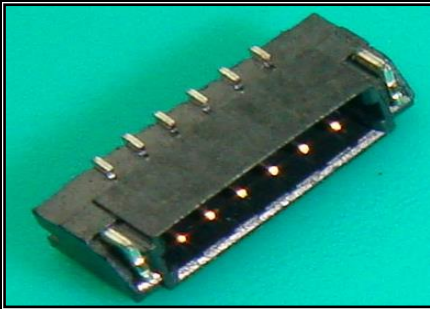
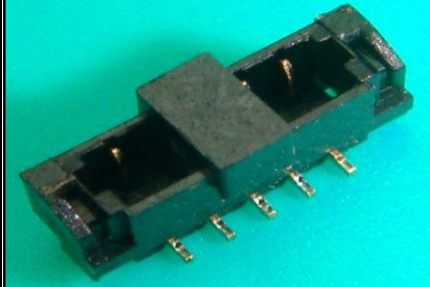
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4.0 Specimen(樣本圖示) :

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
(IDC)Housing JS-ID0600-XX		Wafer Right Angle JS-ID0601H -XXXXX	
		Wafer Straight JS-ID0601V -XXXXX	

5.0 Applicable Standards(適用規範):

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範

6.0 Mechanical Performance(機械性能):

Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.1 Insertion & Withdrawal Force 插入力與拔出力	A socket with correctly terminated wires and a header shall be mated and unmated on the mating axis. Initial insertion and withdrawal forces and withdrawal force at 5 times shall be measured.(testing speed : 1 to 5 mm/sec) 將埋入電線之連接器膠座，以每秒 1 至 5mm 速率，與電路板端連接器連續進行 30 回嵌合與插拔往返測試，並量測首回與 5 回之後拔出力。 (EIA/ECA 364-13D)	Refer to 9.1 Table1. 參照第 9.1 項 表格 1



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
6.2 Wire Retention Force 電線脫離端子之拔出力	Pulling load shall be applied to correctly terminated wire in parallel and perpendicular directions. The load to pull the wire out of the socket or break the wire shall be measured . (testing speed : 1 to 5mm/Sec) Note : It is necessary to use the UV glue for the application of the wire retention force increasing 電線壓接之後為能夠使保持力提昇 , 可於必要時披覆 UV 膠 先以電線末端採正確方向(電線軸向與端子軸向平行)埋入嵌有端子的膠座, 而後以每分鐘 1 至 5mm/min 速率, 測試電線脫離膠座或者未脫離膠座電線即斷裂 , 並量測其最終拔出力。	平行於電線軸方向 之拔出力 Parallel Direction 0.31kgf(Min.) 最小容許值
		垂直於電線軸方向 之拔出力 Perpendicular Direction 0.10kgf(Min.) 最小容許值
6.3 Pin Retention Force(in Base) Pin 針與膠座之間拔出力	The contact mounted in a wafer shall be pulled in the axial direction . The load to pull the contact out of the wafer shall be measured. (Testing speed : 25mm/minute) (EIA 364-29C) 以每分鐘 25mm/min 速率將電路板端連接器當中 Pin 針 , 依原先 Pin 針嵌入膠座之軸向作拔出力測試。	單一接觸點 Per Contact 0.15kgf(Min.) 最小容許值

7.0 Electrical Performance(電氣性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.1 (Low –Signal Level) Contact Resistance (低階信號) 接觸阻抗	A maximum voltage of 20mV and a maximum current of 1 mA(DC) are applied to the mate connector. 對組合狀態下連接器, 於其兩端施以最大電壓 20mV 以及直流電 1mA(DC) 。 (EIA/ECA 364-23C) (Does not include wire resistance 不包含電線阻抗)	Contact Resistance: 30 milliohms Max. 最大容許值. 30m 歐姆
7.2 Insulation Resistance 絕緣阻抗	Apply 100V D/C to any two adjacent contacts to measure the insulation resistance. (EIA 364-21C) 對相鄰兩接觸導體,各施以 100V D/C 電壓以量測其間絕緣阻抗值。	Insulation Resistance: Initial 100 megohms Min 最初容許值. 100 M 歐姆



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.4 Withstanding Voltage 耐電壓	Apply 200V A/C (rms) for 1 minute and the leakage current shall not exceed 0.5mA to the adjacent terminal and ground of the mate connectors. (EIA 364-20C) 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 200V A/C(實效值) 時間 1 分鐘，且漏電流必須小於 0.5mA(毫安培) 。	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. (EIA/ECA 364-28E-Condition 1) 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 Frequency(頻率) : 10-55-10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction. (每一個軸向持續 2 小時)	Initial Contact Resistance : 30 milliohms Max. 接觸阻抗最初容許值: 30m 歐姆 (After the test) Contact Resistance: 50 milliohms Max. 經耐振動試驗後接觸阻抗 : 最大容許值 50m 歐姆 No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於 1 微秒



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.2 Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>(EIA 364-31B Conditions III. Method A)</p> <p>以組合狀態下連接器放置於恆定溫度的濕氣空間，依照隨附如下規格要求，進行恆溫恆濕試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>Temperature(溫度) : 40±2°C.</p> <p>Relative Humidity(相對濕度) : 90%~95% (RH).</p> <p>Period(週期) : 96 hours continuously. (持續 96 小時)</p>	<p>(After the test)</p> <p>Contact Resistance: 50 milliohms Max. 經恆溫恆濕試驗後接觸阻抗： 最大容許值. 50m 歐姆</p> <hr/> <p>(After the test)</p> <p>Insulation Resistance : 100 Megohms Min. 經恆溫恆濕試驗後絕緣阻抗： 最小容許值. 100 M 歐姆</p> <hr/> <p>(After the test)</p> <p>Withstanding Voltage : 經恆溫恆濕試驗後耐電壓： 100V AC</p>
8.3 Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行冷熱衝擊試驗，並於試驗過後量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。</p> <p>(EIA/ECA 364-32D Conditions I. Method A)</p> <p>One Cycle Consists Of:</p> <p>-55°C-3/+0°C for 30 minutes. → Room Temp.5 minutes 85°C+3/-0°C for 30 minutes. → Room Temp.5 minutes</p> <p>Total Cycles: 5 Cycles.</p> <p>以-55°C-3/+0°C溫度持續 30 分鐘，經室溫 5 分鐘，而後再以 85°C+3/-0°C溫度持續 30 分鐘，再經室溫 5 分鐘，構成一次冷熱循環，總計循環次數 5 次。</p>	<p>Same as paragraph 8.2 同 8.2 章節</p>



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Item(項目)		Test Condition(測試條件)	Requirement(規格)
8.4	Heat Aging 高溫老化試驗	<p>A mated connector shall be placed in a heat oven of the following conditions. After the test, contact resistance shall be measured.</p> <p>(EIA 364-17B Conditions III . Method A)</p> <p>以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，並於試驗過後量測其接觸阻抗。</p> <p>Temperature(溫度) : 85±2°C.</p> <p>Period(週期): 96 hours continuously.(持續 96 小時)</p>	<p>Initial Contact Resistance : 30 milliohms Max.</p> <p>接觸阻抗最初容許值:30m 歐姆</p> <p>(After the test)</p> <p>Contact Resistance : 50 milliohms Max. .</p> <p>經高溫老化試驗後接觸阻抗 : 最大容許值. 50m 歐姆</p>
8.5	Salt Spray 鹽水噴霧	<p>A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance.</p> <p>以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。</p> <p>(EIA 364-26B Conditions B)</p> <p>Density(鹽水密度): 5 % in weight.</p> <p>Temperature(溫度): 35±2°C. Period(週期): Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 24 hours)</p>	<p>Initial Contact Resistance : 30 milliohms Max.</p> <p>接觸阻抗最初容許值:30m 歐姆</p> <p>(After the test)</p> <p>Contact Resistance: 50 milliohms Max.</p> <p>經鹽水噴霧試驗後接觸阻抗 : 最大容許值. 50m 歐姆</p>
8.6	Solder Ability 焊錫性	<p>Fluxed soldering section of header shall be dipped in solder of the following conditions. (EIA 364-52B)</p> <p>將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗。</p> <p>Solder Temperature (焊錫溫度) : 245 ± 5°C.</p> <p>Immersion Period (沉浸週期) : 3±0.5 Seconds</p> <p>(操作方式) :</p> <p>零件焊錫位置，距離導體以及固定片末端 0.5mm。</p> <p>Method : 0.5mm From Contact Tip and Solder Nail Tip</p>	<p>Solder entirely (Tin Plated : 95% / Gold Plated : 75%) of immersed area must show no voids or pinholes.</p> <p>焊料覆蓋面積必須達到 (鍍錫 95% / 鍍金 75%)， 而且不能產生氣孔或空隙</p>

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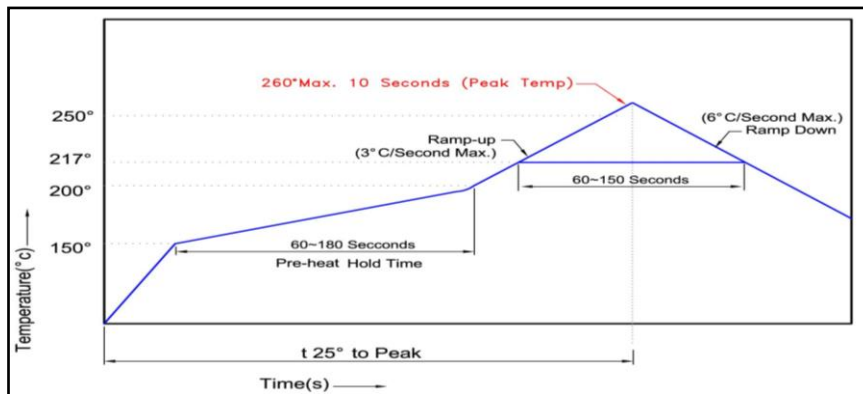


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8.7 Resistance To Soldering Heat 焊錫耐熱性	By reflow soldering 迴焊適用溫度範圍 : Refer to Temperature Profile 請參考 8.7.1 溫度曲線圖 (IPC/JEDEC J-STD-020D.1)	No deformation or damage. 不可有變形或損壞
	By soldering iron 手工烙鐵焊錫適用溫度範圍 : 350 ± 5°C 3±0.5 Seconds. (操作方式): 零件焊錫位置, 距離導體以及固定片末端 0.2mm Method : 0.2mm From Contact Tip and Solder Nail Tip (EIA/ECA 364-56C Procedure 3. Conditions A)	

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試依照客戶需求

8.7.1 Temperature Profile(溫度曲線圖) :



9.0 Tables & Attachments

9.1 Table 1. Insertion Force (I.F.) & Withdrawal Force (W.F.) for user reference:

No. Of Circuits 極數	AT INITIAL 首次嵌入與拔出(初始值)		AT 5 TH 5 次嵌入與拔出之後	No. Of Circuits 極數	AT INITIAL 首次嵌入與拔出(初始值)		AT 5 TH 5 次嵌入與拔出之後
	I.F. (MAX) 嵌入力	W.F. (MIN) 拔出力	W.F. (MIN) 拔出力		I.F. (MAX) 嵌入力	W.F. (MIN) 拔出力	W.F. (MIN) 拔出力
	04	1.32	0.16		0.12	10	1.6
06	1.42	0.20	0.15	12	1.7	0.30	0.24
08	1.53	0.24	0.19				

Unit : Kg/f

10.0 Remark(備註) : Any change or revision for the product specification will not be

announced in advance. Please contact our sales representative for the latest information.

有關規格書內容經變更或改版, 如未能夠及時發佈與通知, 煩請連絡我司業務人員以提供產品最新資訊

Reviewed: J.M.Chang **Approved:** Peter Chang **Verified:** Indiana Huang